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R1540x Series

High Noise Immunity 42 V Input Voltage 70 mA Voltage Tracker for Automotive Applications

NO.EC-513-190411

OVERVIEW

The R1540x is a voltage tracker featuring input voltage in the range of 3.5 V to 42 V. Highly accurate output voltage which attributes to CE/ADJ pin achieves successful sequence control of the integrated off-board sensor module. Strong enough not to require the circuit to avoid external electromagnetic interference (EMI) and this contributes space saving.

KEY BENEFITS

- Excellent noise immunity provides effective shielding against EMI.
- Lower stand-by current consumption leads to energy saving of the whole system to prolong battery life.
- Response to requirements for sequence control in the system with integrated sensors.

KEY SPECIFICATIONS

- Input Voltage Range (Maximum Rating):
 3.5 V to 42.0 V (50.0 V)
- Supply Current: Typ. 60 μA
- Standby Current: Typ. 0.1 μA
- Tracking Voltage Range: 2.2 V to 14 V
- Tracking Voltage Accuracy: ± 15 mV
 (-40°C ≤ Ta ≤ 125°C, V_{CE/ADJ} = 5 V)
- Output Current 70 mA
- Ripple Rejection: Typ. 80 dB (f = 100 Hz)
- Protections: Thermal Shutdown, Output Current Limiting and Short-circuit Current Limiting

PACKAGE

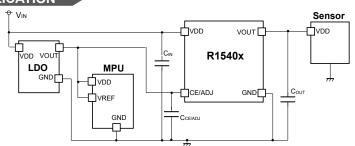


SOT-23-5 2.9 x 2.8 x 1.1 (mm)



HSOP-8E 5.2 x 6.2 x 1.45 (mm)

TYPICAL APPLICATION



 C_{IN} : 0.1uF, C_{OUT} : 10µF, $C_{\text{CE/ADJ}}$: 0.1uF, Ceramic capacitor

SELECTION GUIDE

Product Name	Package	Quantity per Reel
R1540N001B-TR-#E	SOT-23-5	3,000 pcs
R1540S001B-E2-#E	HSOP-8E	1,000 pcs

APPLICATIONS

 Off-board sensors for automotive applications and power supply systems for analog to digital converters (ADC)

SELECTION GUIDE

R1540x offers selectable packages and quality levels corresponding to user's purpose.

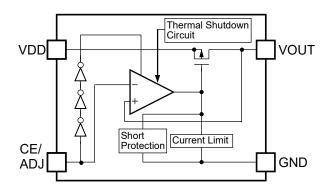
Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R1540N001B-TR-#E	SOT-23-5	3,000 pcs	Yes	Yes
R1540S001B-E2-#E	HSOP-8E	1,000 pcs	Yes	Yes

#: Quality Class

#	Operating Temp. Range	Test Temp.
Α	−40°C to 125°C	25°C, High
K	−40°C to 125°C	Low, 25°C, High

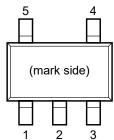
BLOCK DIAGRAM

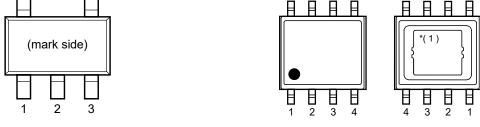


R1540x001B Block Diagram

Bottom View

PIN DESCRIPTIONS





R1540N (SOT-23-5) Pin Configuration

R1540S (HSOP-8E) Pin Configuration

Top View

R1540N Pin Descriptions

Pin No.	Symbol	Description	
1	CE/ADJ	Chip Enable and Adjustment Pin (Active - High)	
2	GND ⁽²⁾	Ground Pin	
3	VDD	Input Pin	
4	VOUT	Output Pin	
5	GND ⁽²⁾	Ground Pin	

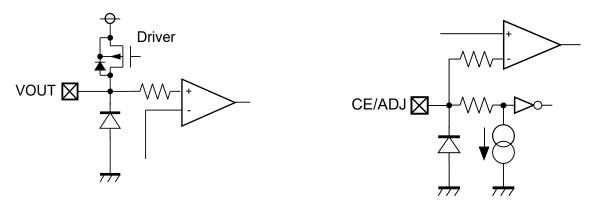
R1540S Pin Descriptions

Pin No.	Symbol	Description	
1	VDD	Input Pin	
2	VDD	Input Pin	
3	NC	No Contact	
4	CE/ADJ	Chip Enable and Adjustment Pin (Active - High)	
5	GND ⁽²⁾	Ground Pin	
6	GND ⁽²⁾	Ground Pin	
7	NC	No Contact	
8	VOUT	Output Pin	

⁽¹⁾ The tab on the bottom of the package is substrate potential (GND). It is recommended that this tab to be connected to the ground plane on the board.

⁽²⁾ The GND pins must be wired together on the board.

INTERNAL EQUIVALENT CIRCUIT FOR EACH PIN



VOUT Pin Internal Equivalent Circuit Diagrams

CE/ADJ Pin Internal Equivalent Circuit Diagrams

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Rating	Unit
\/	Input Voltage		-0.3 to 50	V
V _{IN}	Peak Voltage ⁽¹⁾		60	V
V _{CE/ADJ}	CE/ADJ Pin Input Voltage		-0.3 to 50	V
Vout	VOUT Pin Output Voltage		-0.3 to $V_{IN} + 0.3 \le 50$	V
louт	Output Current		95	mA
D-	Power Dissipation (2)	SOT-23-5	830	m/\/
P _D	JEDEC STD. 51	HSOP-8E	3600	mW
Tj	Junction Temperature Range		-40 to 150	°C
Tstg	Storage Temperature Range		−55 to 150	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings are not assured.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Rating	Unit
VIN	Input Voltage	3.5 to 42	V
V _{CE/ADJ}	CE/ADJ Input Pin Voltage	0 to 14	V
Та	Operating Temperature Range	-40 to 125	°C

RECOMMENDED OPERATING CONDITONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such ratings by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

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⁽¹⁾ Duration time: 200 ms.

⁽²⁾ Refer to POWER DISSIPIATION for detailed information

ELECTRICAL CHARACTERISTICS

 C_{IN} = 0.1 $\mu\text{F},\,C_{\text{OUT}}$ = 10 $\mu\text{F},\,V_{\text{CE/ADJ}}$ = 5.0 V and V_{IN} = 14.0 V, unless otherwise noted.

The specifications surrounded by \square are guaranteed by design engineering at -40°C \leq Ta \leq 125°C.

R1540x001B (-AE) Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Symbol	Parameter	Conditions		Min.	Тур.	Max.	Unit
Iss	Supply Current	V _{IN} = 14 V, I _{OUT} = 0 mA			60	100	μΑ
Istandby	Standby Current	V _{IN} = 42 V, V _{CE/A}	_{DJ} = 0 V		0.1	1.0	μΑ
ΔVο	Tracking Voltage Accuracy	8 V \leq V _{IN} \leq 24 V 1 mA \leq I _{OUT} \leq 70 mA 6 V \leq V _{IN} \leq 42 V 1 mA \leq I _{OUT} \leq 10 mA	- V _{CE/ADJ} = 5.0 V	-15		15	mV
		V _{IN} = 15 V	2.2 V ≤ V _{CE/ADJ} ≤ 5.0 V	-15		15	mV
		I _{OUT} = 1 mA	5.0 V < V _{CE/ADJ} ≤ 14.0 V	-18		18	IIIV
Δ V ουτ /Δ I ουτ	Load Regulation	V _{IN} = 8 V, 1 mA ≤ I _{OUT} ≤ 70 mA		-2		2	mV
ΔV _{OUT} /ΔV _{IN}	Line Regulation	6 V ≤ V _{IN} ≤ 42 V, I _{OUT} = 1 mA		-8		8	mV
ΔV_{OUT}	CE/ADJ Regulation	2.2 V ≤ V _{CE/ADJ} ≤ 14 V, I _{OUT} = 1 mA, V _{IN} = 15 V		-1		1	mV/V
V _{DIF}	Dropout Voltage	I _{OUT} = 70 mA			1.3	2.1	V
I _{LIM}	Output Current Limit	V _{IN} = 8 V		80	120		mA
I _{SC}	Short Current Limit	V _{IN} = 8 V , V _{OUT} = 0 V		20	40		mA
Vce/ADJH	CE/ADJ Pin Input Voltage, high	V _{IN} = 15 V		2.0		14	V
V _{CE/ADJL}	CE/ADJ Pin Input Voltage, low	V _{IN} = 42 V		0		1.0	V
I _{PD}	CE/ADJ Pin Pull Down Current	V _{IN} = 42 V, V _{CE/ADJ} = 2 V			0.2	1.0	μA
T _{TSD}	Thermal Shutdown Detection Temperature	Junction Temperature		150	165		°C
T _{TSR}	Thermal Shutdown Released Temperature	Junction Temper	rature	128	135		°C

All test items listed under Electrical Characteristics are done under the pulse load condition (Tj ≈ Ta = 25°C).



 C_{IN} = 0.1 $\mu\text{F},\,C_{\text{OUT}}$ = 10 $\mu\text{F},\,V_{\text{CE/ADJ}}$ = 5.0 V and V_{IN} = 14.0 V, unless otherwise noted.

R1540x001B (-KE) Electrical Characteristics

(-40°C ≤ Ta ≤ 125°C)

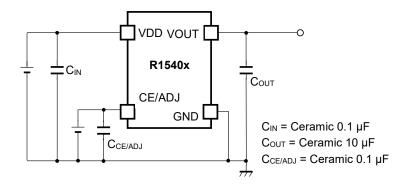
Symbol	Parameter	Conditions		Min.	Тур.	Max.	Unit
Iss	Supply Current	V _{IN} = 14 V, I _{OUT} = 0 mA			60	100	μΑ
Istandby	Standby Current	V _{IN} = 42 V, V _{CE/A}	_{DJ} = 0 V		0.1	1.0	μA
ΔVο	Tracking Voltage Accuracy	$8 \text{ V} \le \text{V}_{\text{IN}} \le 24 \text{ V}$ $1 \text{ mA} \le \text{I}_{\text{OUT}} \le$ 70 mA $6 \text{ V} \le \text{V}_{\text{IN}} \le 42 \text{ V}$ $1 \text{ mA} \le \text{I}_{\text{OUT}} \le$ 10 mA	V _{CE/ADJ} = 5.0 V	-15		15	mV
		V _{IN} = 15 V	2.2 V ≤ V _{CE/ADJ} ≤ 5.0 V	-15		15	>/
		I _{OUT} = 1 mA	5.0 V < V _{CE/ADJ} ≤ 14.0 V	-18		18	mV
Δ V ουτ /Δ I ουτ	Load Regulation	V _{IN} = 8 V, 1 mA ≤ I _{OUT} ≤ 70 mA		-2		2	mV
ΔV _{OUT} /ΔV _{IN}	Line Regulation	6 V ≤ V _{IN} ≤ 42 V, I _{OUT} = 1 mA		-8		8	mV
ΔV _{OUT} /ΔV _{CE/ADJ}	CE/ADJ Regulation	$2.2 \text{ V} \le \text{V}_{\text{CE/ADJ}} \le 14 \text{ V}, \text{ I}_{\text{OUT}} = 1 \text{ mA},$ $\text{V}_{\text{IN}} = 15 \text{ V}$		-1		1	mV/V
V_{DIF}	Dropout Voltage	I _{OUT} = 70 mA			1.3	2.1	V
I _{LIM}	Output Current Limit	V _{IN} = 8 V		80	120		mA
Isc	Short Current Limit	V _{IN} = 8 V , V _{OUT} :	= 0 V	20	40		mA
V _{CE/ADJH}	CE/ADJ Pin Input Voltage, high	V _{IN} = 15 V		2.0		14	V
V _{CE/ADJL}	CE/ADJ Pin Input Voltage, low	V _{IN} = 42 V		0		1.0	V
l _{PD}	CE/ADJ Pin Pull Down Current	V _{IN} = 42 V, V _{CE/ADJ} = 2 V			0.2	1.0	μA
T _{TSD}	Thermal Shutdown Detection Temperature	Junction Temperature		150	165		°C
T _{TSR}	Thermal Shutdown Released Temperature	Junction Temperature		128	135		°C

All test items listed under Electrical Characteristics are done under the pulse load condition (Tj \approx Ta = 25 $^{\circ}$ C).



TYPICAL APPLICATION

TYPICAL APPLICATION



R1540x Typical Application

TECHNICAL NOTES

Phase Compensation

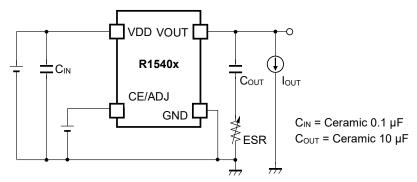
R1540x adopts capacitance and Equivalent Series Resistance (ESR) for phase compensation to ensure stable operation even with load varying current. For this end, the capacitor of 10 μ F or more is essential. A certain amount of ESR may cause unstable output voltage. Fully take temperature and frequency characteristics into consideration when evaluating the circuit. Place the capacitor of 0.1 μ F or more between VDD and GND with using short leads and short printed circuit traces.

PCB Layout

SOT-23-5 package: connect Nos. 2 and 5 of GND pin together. HSOP-8E package: connect Nos. 5 and 6 of GND pin together.

ESR vs. output current characteristics

Using ceramic output capacitor is highly recommended although availability of another low-ESR capacitors. The mutual relations between the output current (I_{OUT}) causes noise under the specified value and the ESR are indicated below for reference.

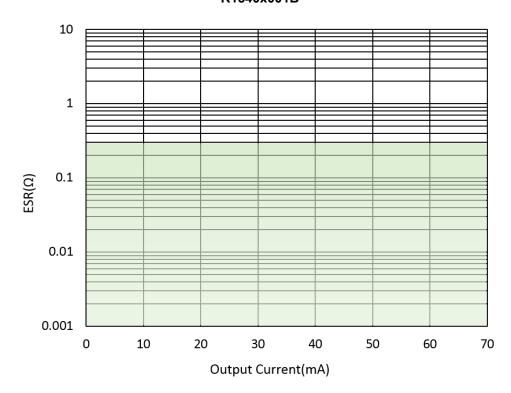


Measurement Conditions

Frequency Band: 10 Hz to 2 MHz Temperature: -40°C to 125°C

Shaded portion: Noise level is 40 μV (average) or below Capacitors: C_{IN} = 0.1 μF of Ceramic, C_{OUT} = 10 μF of Ceramic

R1540x001B



THEORY OF OPERATION

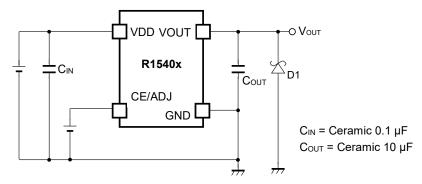
Thermal Shutdown

Thermal Shutdown occurs when the device's junction temperature reaches 165°C (Typ.) at which point the regulator will automatically shut down. Then the regulator resumes from the stand-by state when the junction temperature decreases below 135°C (Typ.). Unless the cause of overheating is eliminated, the device cycles on and off to generate pulse output.

APPLICATION INFORMATION

Typical Application for IC Chip Breakdown Prevention

A sudden surge of current flowing through the VOUT pin during a short to GND leads to negative voltage due to resonance generated between the impedance of the wire and the output capacitor, C2. Consequently, large short-circuit current may destroy the IC or a load device in some types of pattern boards. It is highly recommended to connect schottky diode, D1, between VOUT pin and GND to prevent the IC from being destroyed.



R1540x Typical Application for IC Chip Breakdown Prevention

Electromagnetic Noise Immunity

An output voltage may linearly varies in some regulators due to electromagnetic noise. R1540x adopts the techniques on its circuits to prevent this voltage variation. The noise immunity test indicated below was conducted to confirm that R1540x is fairly robust to electromagnetic noise over a broad frequency band.

DC power supply : apply $V_{IN} = 14 \text{ V}$, $V_{CE/ADJ} = 5 \text{ V}$

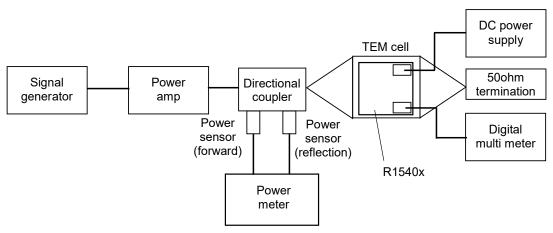
Digital multi meter: measure the output DC voltage of R1540 Signal generator: apply high frequency signal of 150 kHz to 1 GHz

3.5

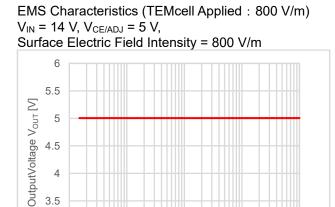
0.1

Power meter: measure the intensity of signal so as to sense the surface electric field intensity of 800

V/m



Block Diagram for Immunity Test Based on IEC 62132-2 TEM cell



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frequency [MHz]

100

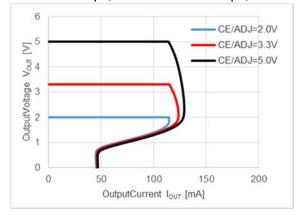
1000

TYPICAL CHARACTERISTICS

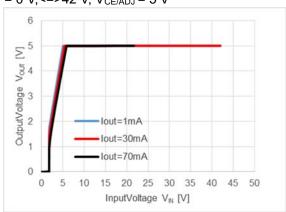
Typical Characteristics are intended to be used as reference data, they are not guaranteed

1) Output voltage vs Output Current

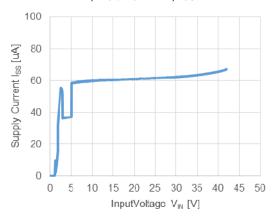
 C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta = 25°C

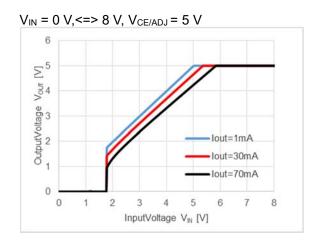


2) Output voltage vs Input Voltage C_{IN} = Ceramic 0.1 $\mu F,~C_{OUT}$ = Ceramic 10 μF , Ta=25°C V_{IN} = 0 V,<=>42 V, $V_{CE/ADJ}$ = 5 V

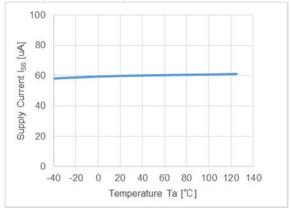


3) Supply Current vs Input Voltage C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, T_{A} = 25°C V_{IN} = 0 V <=>42 V, $V_{CE/ADJ}$ = 5 V, I_{OUT} = 0 mA

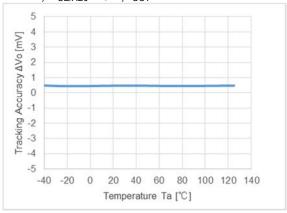




4) Supply Current vs Temperature C_{IN} = Ceramic 0.1 μF , C_{OUT} = Ceramic 10 μF V_{IN} = 14 V, $V_{CE/ADJ}$ = 5 V, I_{OUT} = 0 mA

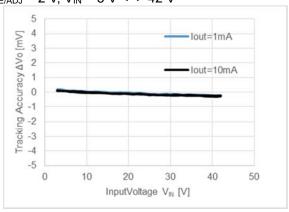


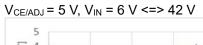
5) Tracking Accuracy vs Temperature C_{IN} = Ceramic 0.1 μF , C_{OUT} = Ceramic 10 μF $V_{IN} = 14 \text{ V}, V_{CE/ADJ} = 5 \text{ V}, I_{OUT} = 1 \text{ mA}$

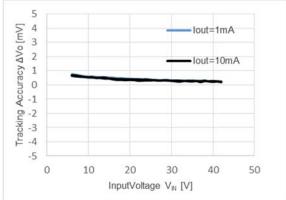


6) Tracking Accuracy vs Input Voltage C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta=25°C

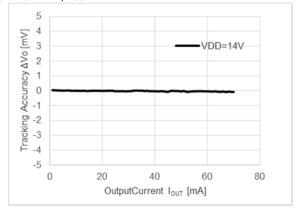
 $V_{CE/ADJ} = 2 \text{ V}, V_{IN} = 3 \text{ V} <=> 42 \text{ V}$



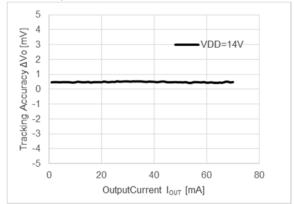




7) Tracking Accuracy vs Load Current C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta = 25°C $V_{CE/ADJ}$ = 2 V, I_{OUT} = 1mA <=> 70 mA

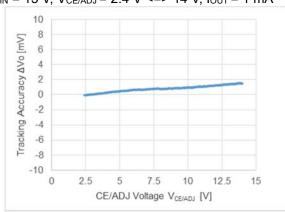


 $V_{CE/ADJ} = 5 V$, $I_{OUT} = 1mA <=> 70 mA$

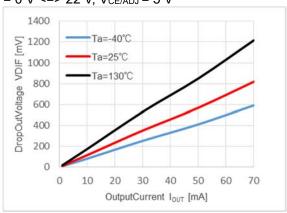


8) Tracking Accuracy vs CE/ADJ Voltage C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta = 25°C

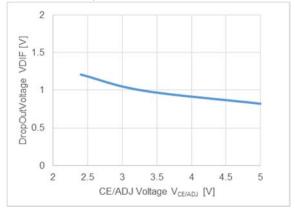
 V_{IN} = 15 V, $V_{CE/ADJ}$ = 2.4 V <=> 14 V, I_{OUT} = 1 mA



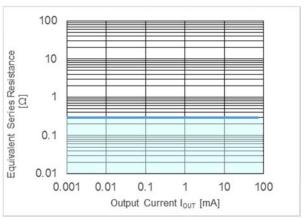
9) Dropout Voltage vs Output Current C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta=25°C V_{IN} = 0 V <=> 22 V, $V_{CE/ADJ}$ = 5 V



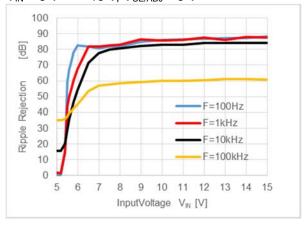
10) Dropout Voltage vs CE/ADJ Voltage C_{IN} = Ceramic 0.1 $\mu\text{F},~C_{\text{OUT}}$ = Ceramic 10 $\mu\text{F},~Ta=25^{\circ}\text{C}$ V_{IN} = 0 V <=>22 V, I_{OUT} =70 mA



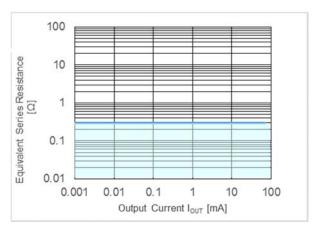
11) Equivalent Series Resistance vs Output Current C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta=25°C V_{IN} = 4 V <=> 42 V, $V_{CE/ADJ}$ = 2 V Ta =-40°C / 25°C / 130°C



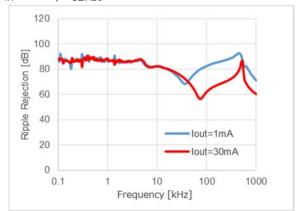
12) Ripple Rejection vs Input Voltage C_{IN} = none, C_{OUT} = Ceramic 10 μ F, Ta = 25°C V_{IN} = 5 V <=> 15 V, $V_{CE/ADJ}$ = 5 V



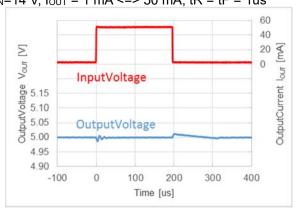
 $V_{IN} = 7 \text{ V} \iff 42 \text{ V}, V_{CE/ADJ} = 5 \text{ V}$ Ta=-40°C / 25°C / 130°C



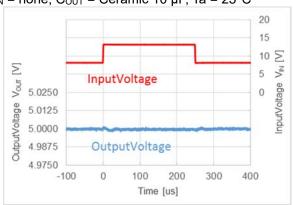
13) Ripple Rejection vs Frequency C_{IN} = none, C_{OUT} = Ceramic 10 μ F, Ta = 25°C V_{IN} = 14 V, $V_{CE/ADJ}$ = 2 V



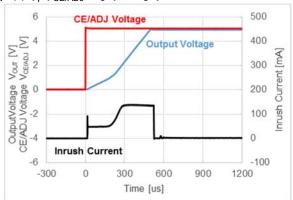
14) Load Transient Response C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta = 25°C V_{IN} =14 V, I_{OUT} = 1 mA <=> 50 mA, tR = tF = 1us



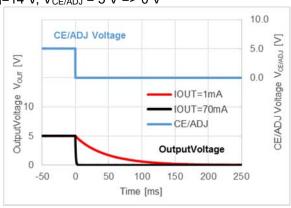
15) Input Transient Response C_{IN} = none, C_{OUT} = Ceramic 10 μ F, Ta = 25°C



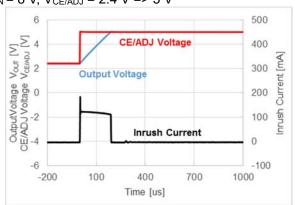
16) Turn-on Speed with CE/ADJ pin C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta = 25°C V_{IN} =14 V, $V_{CE/ADJ}$ = 0 V => 5 V



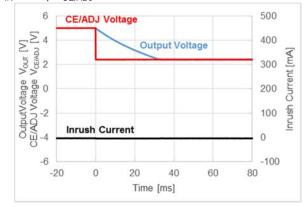
17) Turn-off Speed with CE/ADJ pin C_{IN} = Ceramic 0.1 $\mu\text{F},\,C_{\text{OUT}}$ = Ceramic 10 $\mu\text{F},\,Ta$ = 25°C V_{IN} =14 V, $V_{\text{CE/ADJ}}$ = 5 V => 0 V



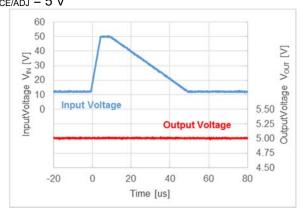
18) CE/ADJ Excess/Inrush Current C_{IN} = none, C_{OUT} = Ceramic 10 μ F, Ta = 25°C V_{IN} = 8 V, $V_{CE/ADJ}$ = 2.4 V => 5 V



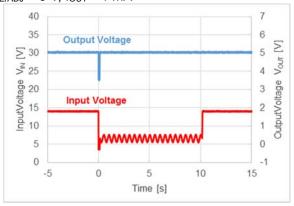
 $V_{IN} = 8 \text{ V}, V_{CE/ADJ} = 5 \text{ V} => 2.4 \text{ V}$



19) Load Dump C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta = 25°C $V_{CE/ADJ} = 5 V$

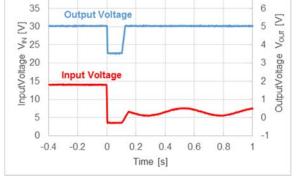


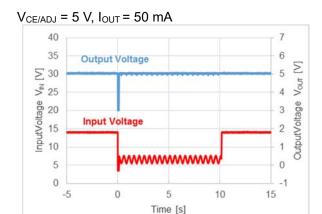
20) Cranking C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 10 μ F, Ta = 25°C $V_{CE/ADJ} = 5 V, I_{OUT} = 1 mA$

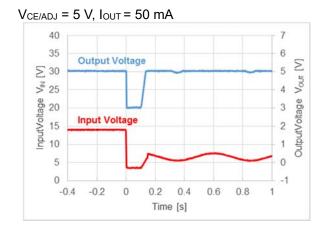


40 35 **Output Voltage** ≥30 $\frac{z}{25}$

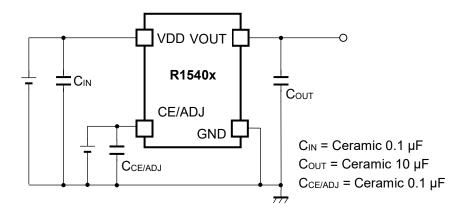
 $V_{CE/ADJ} = 5 V, I_{OUT} = 1 mA$







Test Circuit



R1540x circuit for measuring Typical Characteristics

Measurement Components of Typical Characteristics

Symbol	Capacitance	Measurement item	Manufacturer	Parts number
Cin	0.1 μF	All	TDK	CGA4J2X7R2A104K125AA
Соит	10 μF	All	TDK	CGA6P1X7R1E106K

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

Item Measurement Conditions		
Environment	Mounting on Board (Wind Velocity = 0 m/s)	
Board Material Glass Cloth Epoxy Plastic (Four-Layer Board)		
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm	
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square	
Through-holes	φ 0.3 mm × 7 pcs	

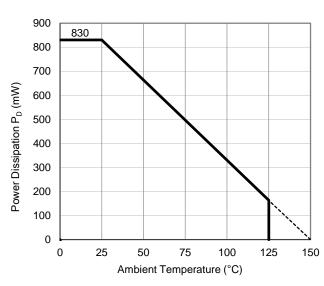
Measurement Result

(Ta = 25°C, Tjmax = 150°C)

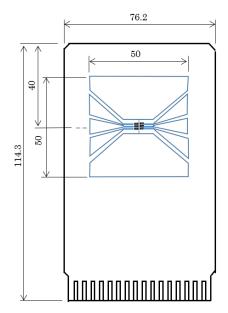
Item	Measurement Result
Power Dissipation	830 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

 θ ja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter

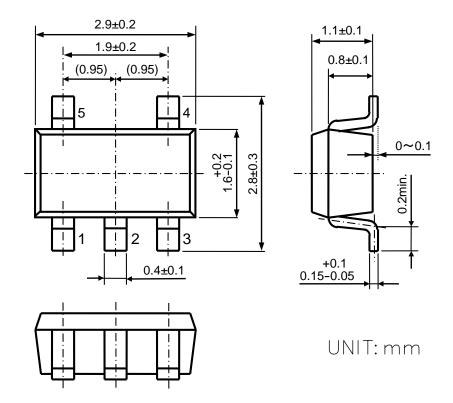


Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

Ver. A



SOT-23-5 Package Dimensions

Ver. B

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

Item	Measurement Conditions	
Environment	Mounting on Board (Wind Velocity = 0 m/s)	
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)	
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm	
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square	
Through-holes	φ 0.3 mm × 21 pcs	

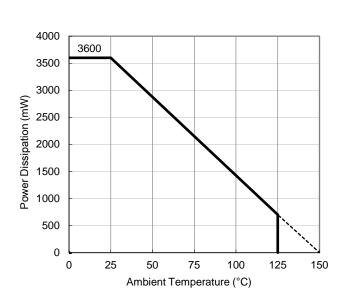
Measurement Result

 $(Ta = 25^{\circ}C, Tjmax = 150^{\circ}C)$

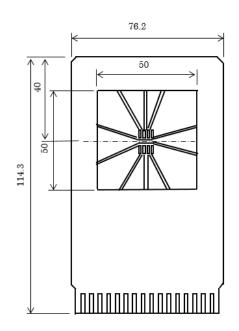
Item	Measurement Result
Power Dissipation	3600 mW
Thermal Resistance (θja)	θja = 34.5°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 10°C/W

θja: Junction-to-Ambient Thermal Resistance

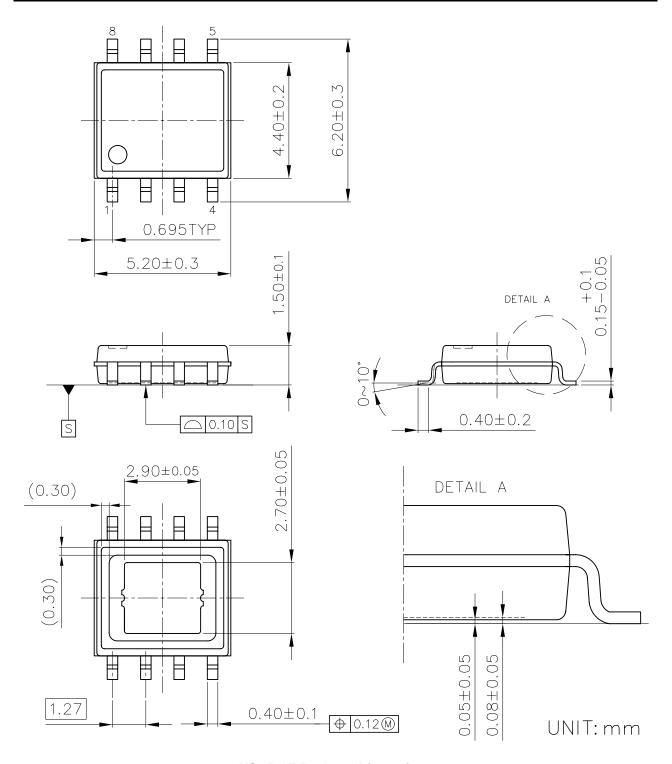
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



HSOP-8E Package Dimensions

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